

Tech-X Corporation is proud to be an exhibitor at the [37th IEEE International Conference on Plasma Science](#), being held **June 20 – 24** at the Marriott Waterside in **Norfolk, VA**. Please stop by our booth (booth #3) where we will be presenting our electromagnetic plasma simulation software, [VORPAL](#). VORPAL 4.0 provides for the first time parallel and multi-core capability to the Windows platform (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer or your cluster hardware. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization